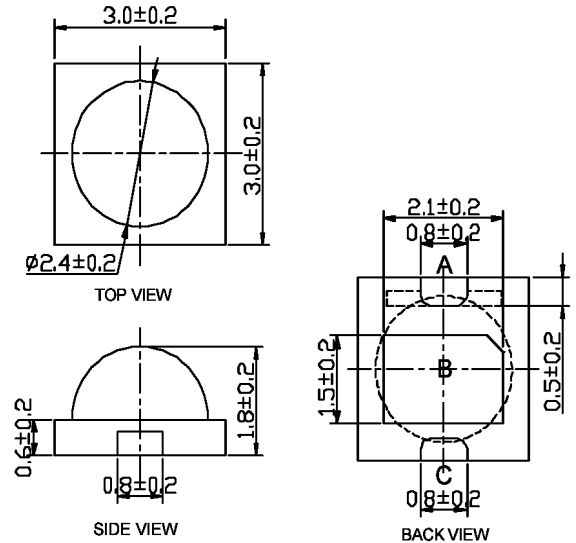


## LD-300DPG1-C5

### Features

Designed for High Current Operation  
 Exposed Pad Design for Excellent Heat Transfer  
 High Luminous Flux Output for Illumination  
 Reflow Solderable  
 Clear Compound Encapsulation



A : CATHODE  
 B : HEAT SINK  
 C : ANODE

### Maximum Ratings (Ta=25°C)

Characteristic	Symbol	Max.	Unit
Forward Current	I <sub>F</sub>	60	mA
Reverse Voltage	V <sub>R</sub>	5	V
Power Dissipation	P <sub>D</sub>	0.246	mW
Operating Temperature	T <sub>opr</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	°C
Soldering Temperature	T <sub>sol</sub>	260	°C
Soldering Time	-	for 3 sec. max	-

### Opto-Electrical Characteristics (Ta=25°C)

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =60mA	-	3.80	4.40	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	-	-	10	μA
Luminous Intensity	I <sub>v</sub>	I <sub>F</sub> =60mA	3.00	5.50	-	lm
Viewing Angle	2θ <sup>1/2</sup>	-	-	125°	-	deg.
Peak Wavelength	λ <sub>p</sub>	I <sub>F</sub> =60mA	-	520	-	nm
Dominant Wavelength	λ <sub>d</sub>	I <sub>F</sub> =60mA	-	525	-	nm
Spectral Line Half Width	Δλ	I <sub>F</sub> =60mA	-	38	-	nm

## LD-300DPG1-C5 Graphs

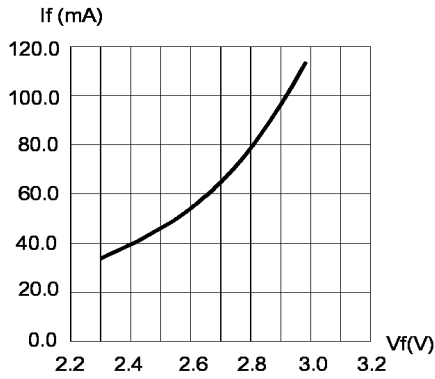


FIG.1 FORWARD CURRENT VS. FORWARD VOLTAGE.

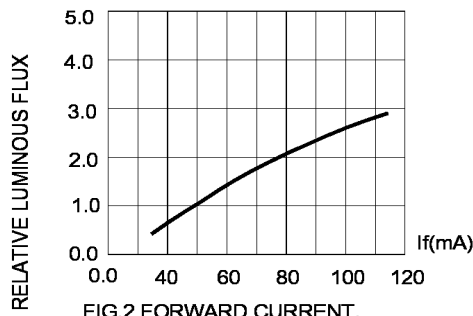


FIG.2 FORWARD CURRENT.

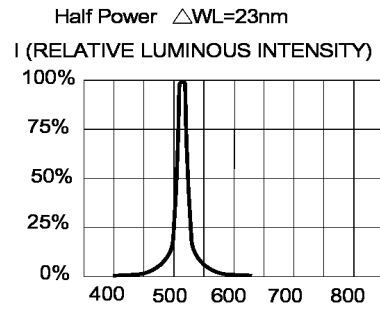


FIG.3 RELATIVE LUMINOUS FLUX VS. WAVELENGTH.

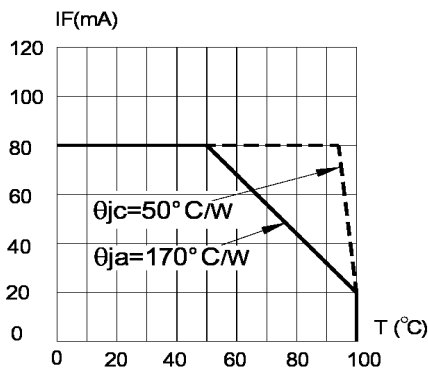


FIG.4 MAXIMUM FORWARD DC CURRENT VS TEMPERATURE. DERATING BASED ON  $T_{jmax} = 110^\circ \text{C}$

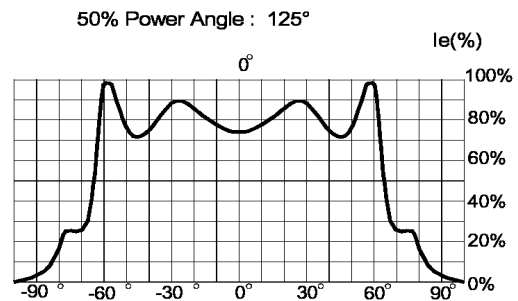


FIG.5 SPATIAL DISTRIBUTION.